

L Number	Hits	Search Text	DB	Time stamp
1	2	("5451818").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 07:56
2	0	("solder near3 MMIC adj chip").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 07:56
3	7	solder near3 MMIC adj chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 08:12
4	3	silver adj epoxy near6 MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 08:13
5	3	silver adj epoxy near12 chip and MMIC.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 08:14
6	5	silver adj epoxy near12 (die or chip) and (monolithic adj microwave or MMIC).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 08:15
7	6	silver adj epoxy near12 (die or chip) and (monolithic adj microwave or MMIC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 08:21
8	16	solder near4 preform and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 08:21
9	13	solder near4 preform and MMIC.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 08:31
10	1	(radio-frequency or radio adj frequency or rf) adj (lid or cover) near15 (MMIC or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 08:34
11	1	(radio-frequency or radio adj frequency or rf or kovar) adj (lid or cover) near15 (MMIC or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 08:34
12	2	(radio-frequency or radio adj frequency or rf or kovar) near4 (lid or cover) near15 (MMIC or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:03
13	158	isolation near3 (via or through-hole or through adj hole) and (chip or die).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:05
14	20	isolation adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:05

15	5	isolation adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm. and (mmic or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:07
16	6	(insulation or isolation or insulating or isolating) adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm. and (mmic or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:11
17	47	isolation adj via.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:12
18	1	isolation adj via.ti,ab,clm. and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:12
19	6	isolation adj via.ti,ab,clm. and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:17
20	1	(isolation adj via or isolation adj trench).ti,ab,clm. and (chip or die) and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:18
21	3097	mmic and sti or isolation adj trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:19
22	0	(isolation adj trench or sti) same mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:19
23	112	(isolation adj trench or sti) same chip and (integrated adj circuit or ic).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:20
24	4	(isolation adj trench or sti) and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:31
25	12	epoxy near1 silver and integrated adj circuit and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:32
-	0	mmic.ti. and transceiver.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:25
-	15	mmic.ti. and transceiver	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 14:12
-	1	mmic.ti. and transceiver and (tuned or tuning)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 14:13

-	0	mmic.ti. and transceiver.ti,ab,clm. and (tuned or tuning).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/14 14:15
-	2	(mmic or microwave adj monolithic).ti. and transceiver.ti,ab,clm. and (tuned or tuning).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/14 14:44
-	0	(mmic or microwave adj monolithic).ti. and transceiver.ti,ab,clm. and 438/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/14 14:44
-	20	(mmic or microwave adj monolithic).ti. and 438/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/14 14:44
-	370	integrated adj circuit adj board.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/17 12:07
-	7	integrated adj circuit adj board.ti. and integrated adj circuit adj board.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/17 12:08
-	634	(455/73).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/20 16:25
-	147	(257/277).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/20 16:25
-	551	(257/728).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/20 16:26
-	1978	(mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/20 16:26
-	1325	((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/20 16:27
-	70	((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) and (((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/20 16:27
-	3233	((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) or (((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/20 16:27
-	221	((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) or (((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.)) and transceiver.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/20 16:28

-	8	((US-5451818-\$ or US-6441449-\$ or US-5423080-\$ or US-6124636-\$ or US-5545924-\$ or US-6257058-\$ or US-6278159-\$ or US-6278337-\$ or US-6201728-\$ or US-6124765-\$ or US-6424074-\$ or US-6073484-\$ or US-6268779-\$).did. or (US-20010001224-\$).did. or (EP-504020-\$ or JP-11214578-\$ or EP-712534-\$ or WO-200223674-\$ or WO-200075762-\$).did.) and thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:05
-	18	(monolithic adj microwave or mmic).ti. and ((thick or thickness) same mil)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:07
-	0	(monolithic adj microwave or mmic).ti. and ((thick or thickness) near12 mil near12 base)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:08
-	17	(monolithic adj microwave or mmic).ti. and ((thick or thickness) near12 mil)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:12
-	25	cte near4 gaas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:50
-	2	("5451818").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:50